S105T01/S105T02 S205T01/S205T02

■ Features

1. Low profile type (height: 16mm)

2. Built-in zero-cross circuit (S105T02/S205T02)

3. RMS ON-state current IT: MAX. 5Arms

4. Approved by TÜV, No. R9750790 (S205TY1/S205TY2)

Input-Output: Basic Insulation

■ Applications

1. Programmable controllers

2. Air conditioners

3. Copiers

4. Automatic vending machines

■ Model line-ups

	For 100V lines	For 200V lines
No zero-cross circuit	S105T01	S205T01
Built-in zero-cross circuit	S105T02	S205T02

■ Absolute Maximum Ratings

$(T_0 -$	2500	17
(1a-	23 C	, ,

Parameter			Symbol	Rating	Unit	
Input	Forward current		IF	50	mA	
Inp	Reverse voltage		V_R	6	V	
Output	RMS ON-state current		Iτ	*15	Arms	
	*2 Peak one cycle surge current		Isurge	50	A	
	Repetitive peak	S105T01 S105T02	*7	400	V	
	OFF-state voltage	S205T01 S205T02	V _{DRM}	600		
	Non-repetitive peak	S105T01 S105T02	3.7	400	V	
	OFF-state voltage	S205T01 S205T02	V _{DSM}	600	V	
	Critical rate of rise of ON-state current		dΙτ/dt	50	A/μs	
	Operating frequency		f	45 to 65	Hz	
Operating temperature		Topr	-25 to +100	°C		
Storage temperature		Tstg	-30 to +125	°C		
*3 Isolation voltage		Viso	3.0	kVrms		
*4 Soldering temperature		Tsol	260	°C		

^{*1} Refer to Fig.2, Fig.3

- (1) Dielectric withstand voltage tester with zero cross circuit shall be used.
- (2) The applied voltage waveform shall be sine wave.
- (3) Voltage shall be applied between input and output. (Input and output terminals shall be shorted respectively.)

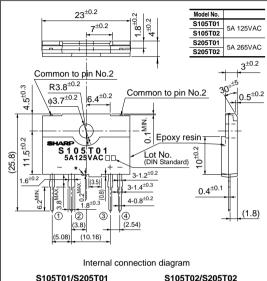
(4) AC 60Hz, 1min, 40 to 60%RH.

*4 For 10s

Low Profile Type Solid State Relays

■ Outline Dimensions

(Unit: mm)





- ① Output (Triac T1)
- ② Output (Triac T2) ③ Input (+)
- 4 Input (-)

1 (2) (3)(4)

- Z.C.: Zero-cross circuit
 - ① Output (Triac T1)
 - 2 Output (Triac T2)
 - ③ Input (+)
- 4 Input (-)
- *: Do not allow external connection. * (): Typical dimensions

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^{*2 60}Hz sine wave, start at Tj=25°C

^{*3} Isolation voltage measuring method

■ Electro-optical Characteristics (Ta=25°C)								
	Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage V _F		$V_{\rm F}$	I _F =20mA	-	1.2	1.4	V
	Reverse current		IR	V _R =3V	ı	ı	1×10 ⁻⁴	A
	Repetitive peak OFF-state current		Idrm	V _D =V _{DRM}	_	-	1×10 ⁻⁴	A
	ON-state voltage		V_{T}	I _T =2A _{rms} , Resistance load, I _F =20mA	_	-	1.5	V _{rms}
	Holding current		I_{H}	_	_	_	50	mA
Output	Critical rate of rise of OFF-state voltage		dV/dt	$V_D=2/3V_{DRM}$	30	ı	-	V/µs
Out	Critical rate of rise of OFF-state voltage at commutaion		(dV/dt)c	T _j =125°C, V _D =2/3V _{DRM} , dI _v /dt=-2.5A/ms	5	_	_	V/µs
	Minimum	S105T01/S205T01	IFT	V _D =12V, R _L =30Ω			8	mA
S		S105T02/S205T02	1FT	V _D =6V, R _L =30Ω	_			
stic	Zero cross voltage S105T02/S205T02 Vox		Vox	I _F =8mA	_	-	35	V
Transfer characteristics	Isolation resistance		Riso	DC500V, 40 to 60%RH	1×10 ¹⁰	-	_	Ω
	Turn-on time S	S105T01	ton	VD=100Vrms, AC50Hz, IT=2Arms,	_	_	1	
ch		S105T02		Resistance load, I _F =20mA	_	- 10		ms
sfer		S205T01		VD=200Vrms, AC50Hz, IT=2Arms,	_	-	1	ms
ran		S205T02		Resistance load, I _F =20mA	_	_	10	
T		S105T01	V _D =100V _{rms} , AC50Hz, I _T =2A _{rms} ,		_	10	ms	
	Turn-off time S105T02 S205T01	toff	Resistance load, I _F =20mA	_				
			VD=200Vrms, AC50Hz, IT=2Arms,					
		S205T02		Resistance load, I _F =20mA				
Thermal resistance (Between junction and case)		Rth(j-c)	_	_	5	_	°C/W	
Thermal resistance (Between junction and ambience)		Rth(j-a)	_	_	45	_	°C/W	

Fig.1 Forward Current vs. Ambient Temperature

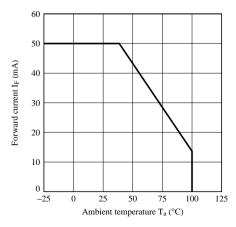


Fig.2 RMS ON-state Current vs. Ambient Temperature

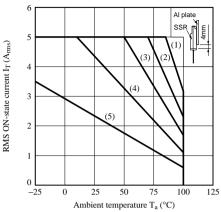


Fig.3 RMS ON-state Current vs. Case Temperature

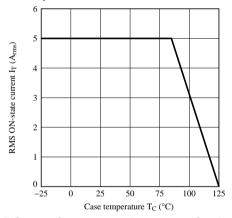
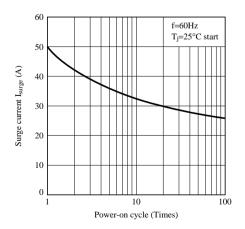


Fig.5 Surge Current vs. Power-on Cycle



- (1) With infinite heat sink
- (2) With heat sink (200×200×2mm Al plate)
- (3) With heat sink (100×100×2mm Al plate)
- (4) With heat sink (50×50×2mm Al plate)
- (5) Without heat sink

(Note) With the Al heat sink set up vertically, tighten the device with a torque of 0.4N•m and apply thermal conductive silicone grease on the mounting face of heat sink. Forced cooling shall not be carried out. (Please use an isolation sheet if necessary.)

Fig.4 Forward Current vs. Forward Voltage

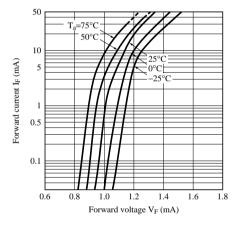


Fig.6 Minimum Trigger Current vs. Ambient Temperature (Typical Value)

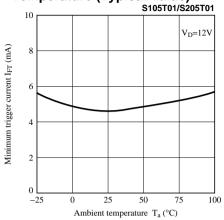


Fig.8 Maximum ON-state Power Dissipation vs. RMS ON-state Current (Typical Value)

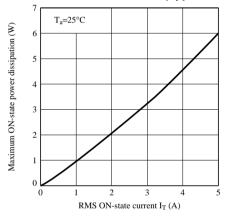


Fig.9 Repetitive Peak OFF-state Current vs. Ambient Temperature

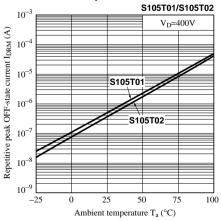


Fig.7 Minimum Trigger Current vs. Ambient Temperature (Typical Value)

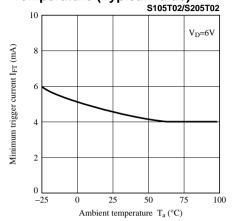
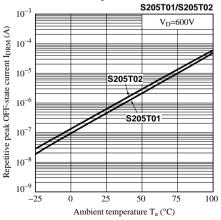


Fig.10 Repetitive Peak OFF-state Current vs. Ambient Temperature



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